



30V N&P-Channel Trench Power MOSFET

General Description

The SJP4606 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as $\pm 4.5V$. This device is suitable for use as a wide variety of applications.

Features

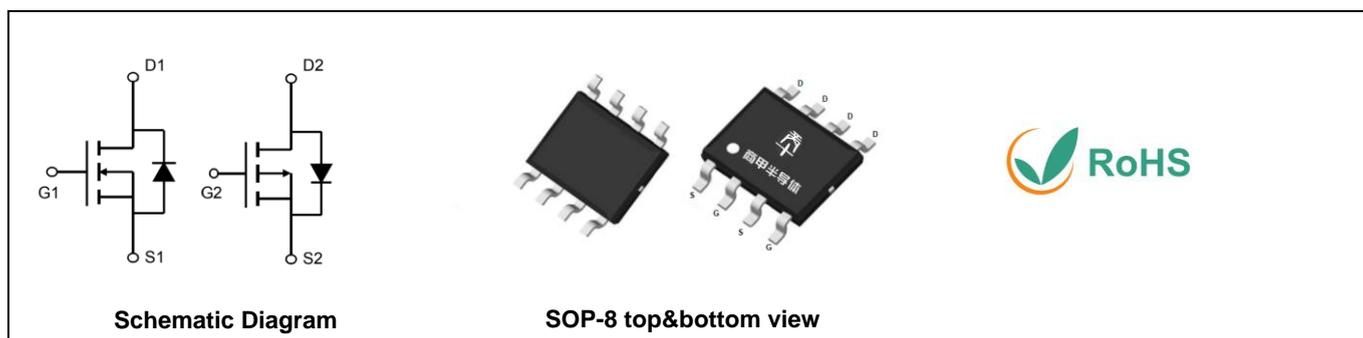
- Low Gate Charge
- High Power and current handing capability
- Lead free product is acquired

Application

- Battery Protection
- Power Management
- Load Switch

Key Performance Parametes

Parameter	Value	Value	Unit
V_{DS}	30	-30	V
$R_{DS(ON_TYP)}$	12	30	m Ω
I_D	11.2	-7	A
Q_G	14	16	nC



Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJP4606	SJP4606	SOP-8	Tape	\	\	4000 Pcs

Table 1. Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	N Limit	P Limit	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	30	-30	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 20	± 20	V
I_D	Drain Current-Continuous($T_A=25^\circ C$)	11.2	-7	A
	Drain Current-Continuous($T_A =100^\circ C$)	7.1	-4.4	A
I_{DM} (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	44.8	-28	A
P_D	Maximum Power Dissipation($T_A =25^\circ C$)	3	2.9	W
	Maximum Power Dissipation($T_A =100^\circ C$)	1.2	1.2	W
E_{AS}	Avalanche energy (Note 2)	36	30	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150		$^\circ C$

Table 2. Thermal Characteristic

Symbol	Parameter	N Max	P Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to- Ambient	42.3	43	$^\circ C/W$



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Table 3. N-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V, T_J=25^\circ\text{C}$			1	μA
		$V_{DS}=30V, V_{GS}=0V, T_J=125^\circ\text{C}$			100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0		2.5	V
g_{FS}	Forward Transconductance	$V_{DS}=5V, I_D=3A$		6.4		S
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=3A, T_J=25^\circ\text{C}$		12	15	m Ω
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=4.5V, I_D=2A, T_J=25^\circ\text{C}$		18.1	24.1	m Ω
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1.0\text{MHz}$		600		pF
C_{oss}	Output Capacitance			75		pF
C_{rss}	Reverse Transfer Capacitance			61		pF
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V, f=1.0\text{MHz}$		1.2		Ω
Switching Parameters						
$t_{d(on)}$	Turn-on Delay Time	$V_{GS}=10V, V_{DS}=15V, R_L=5\Omega, R_{GEN}=3\Omega$		4.5		nS
t_r	Turn-on Rise Time			2.5		nS
$t_{d(off)}$	Turn-Off Delay Time			14.5		nS
t_f	Turn-Off Fall Time			3.5		nS
Q_g	Total Gate Charge	$V_{GS}=10V, V_{DS}=15V, I_D=3A$		14		nC
Q_{gs}	Gate-Source Charge			2		nC
Q_{gd}	Gate-Drain Charge			3		nC
Source-Drain Diode Characteristics						
I_{SD}	Source-Drain Current (Body Diode)				11.2	A
V_{SD}	Forward on Voltage (Note 3)	$V_{GS}=0V, I_S=3A$			1.2	V
t_{rr}	Reverse Recovery Time	$I_F=3A, dI/dt=500A/\mu s$		10		ns
Q_{rr}	Reverse Recovery Charge	$I_F=3A, dI/dt=500A/\mu s$		5		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

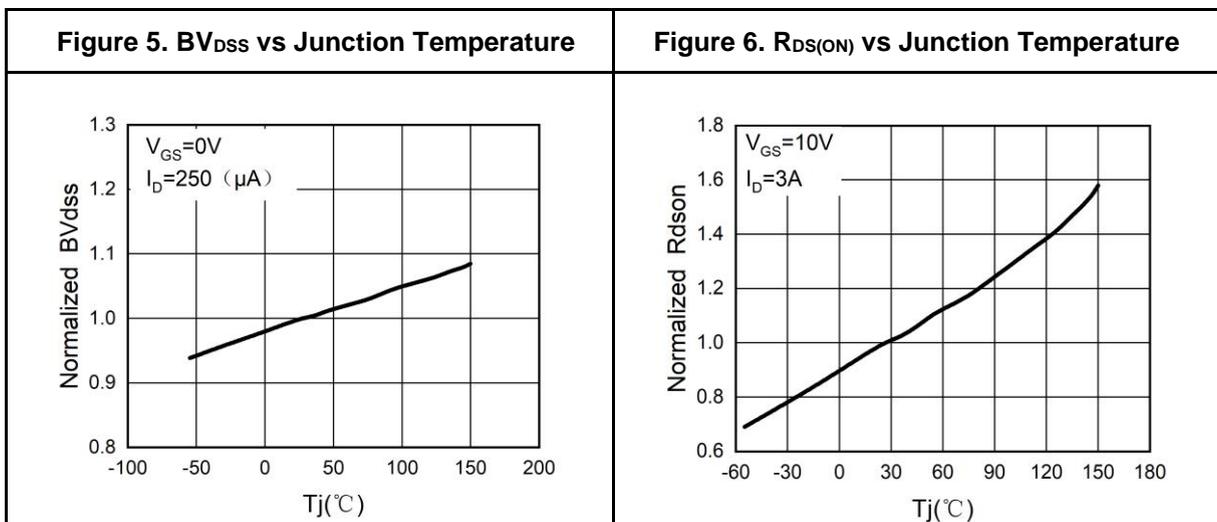
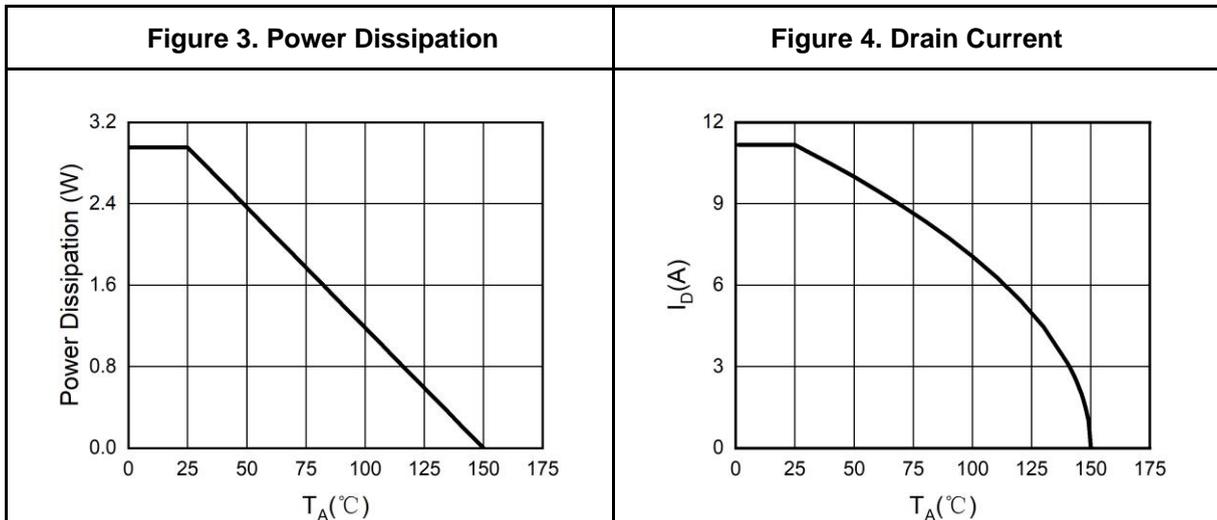
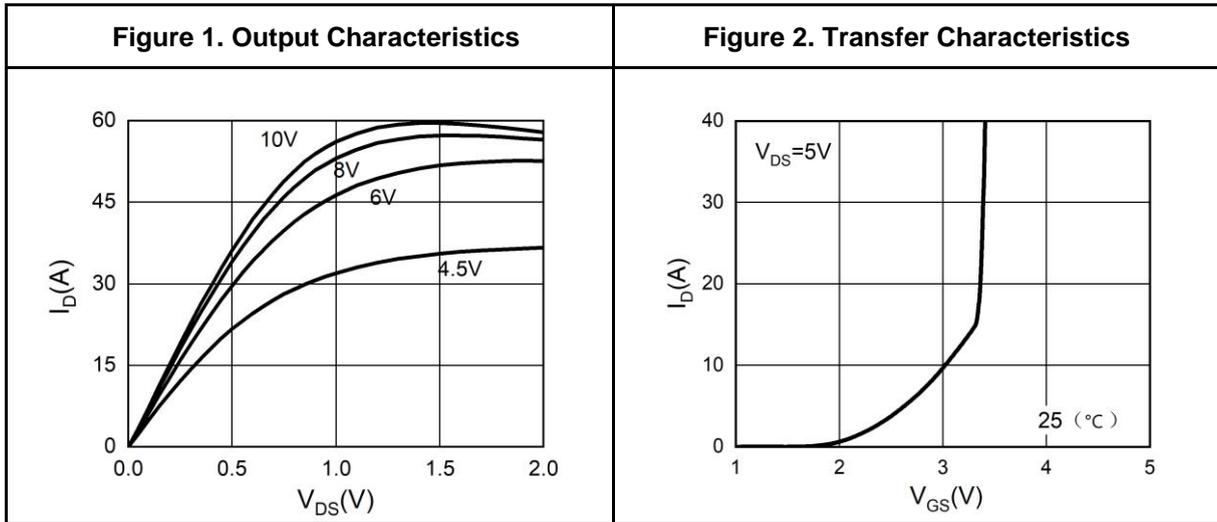
Notes 2.EAS condition: $T_J=25^\circ\text{C}, V_{DD}=30V, V_G=10V, R_g=25\Omega, L=0.5\text{mH}$.

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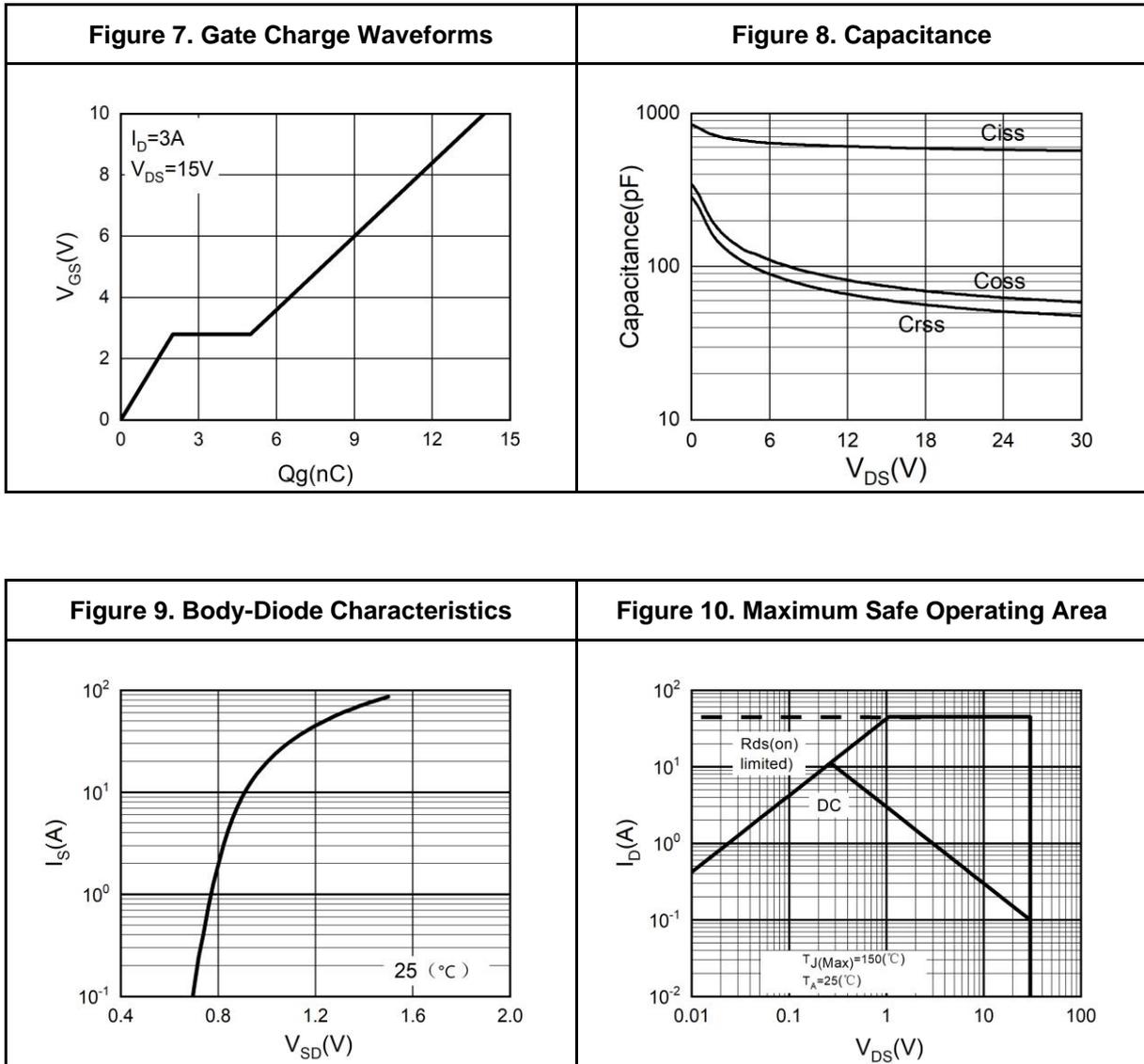
N-Channel Typical Electrical And Thermal Characteristics (Curves)





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N-Channel Typical Electrical And Thermal Characteristics (Curves)





30V N&P-Channel Trench Power MOSFET

Table 4. P-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30V, V_{GS}=0V, T_J=25^\circ\text{C}$			-1	μA
		$V_{DS}=-30V, V_{GS}=0V, T_J=125^\circ\text{C}$			-100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1		-2.5	V
g_{FS}	Forward Transconductance	$V_{DS}=-5V, I_D=-2A$		4.8		S
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=-10V, I_D=-2A, T_J=25^\circ\text{C}$		30	37.5	m Ω
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=-4.5V, I_D=-1.5A, T_J=25^\circ\text{C}$		37.9	50.4	m Ω
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, f=1.0\text{MHz}$		617		pF
C_{oss}	Output Capacitance			79		pF
C_{rss}	Reverse Transfer Capacitance			63		pF
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V, f=1.0\text{MHz}$		6.5		Ω
Switching Parameters						
$t_{d(on)}$	Turn-on Delay Time	$V_{GS}=-10V, V_{DS}=-15V, R_L=7.5\Omega, R_{GEN}=3\Omega$		7.5		nS
t_r	Turn-on Rise Time			5.5		nS
$t_{d(off)}$	Turn-Off Delay Time			19		nS
t_f	Turn-Off Fall Time			7		nS
Q_g	Total Gate Charge	$V_{GS}=-10V, V_{DS}=-15V, I_D=-2A$		16		nC
Q_{gs}	Gate-Source Charge			2		nC
Q_{gd}	Gate-Drain Charge			4		nC
Source-Drain Diode Characteristics						
I_{SD}	Source-Drain Current (Body Diode)				-7	A
V_{SD}	Forward on Voltage (Note 3)	$V_{GS}=0V, I_S=-2A$			-1.2	V
t_{rr}	Reverse Recovery Time	$I_F=3A, dI/dt=500A/\mu s$		15		ns
Q_{rr}	Reverse Recovery Charge	$I_F=3A, dI/dt=500A/\mu s$		10		nC

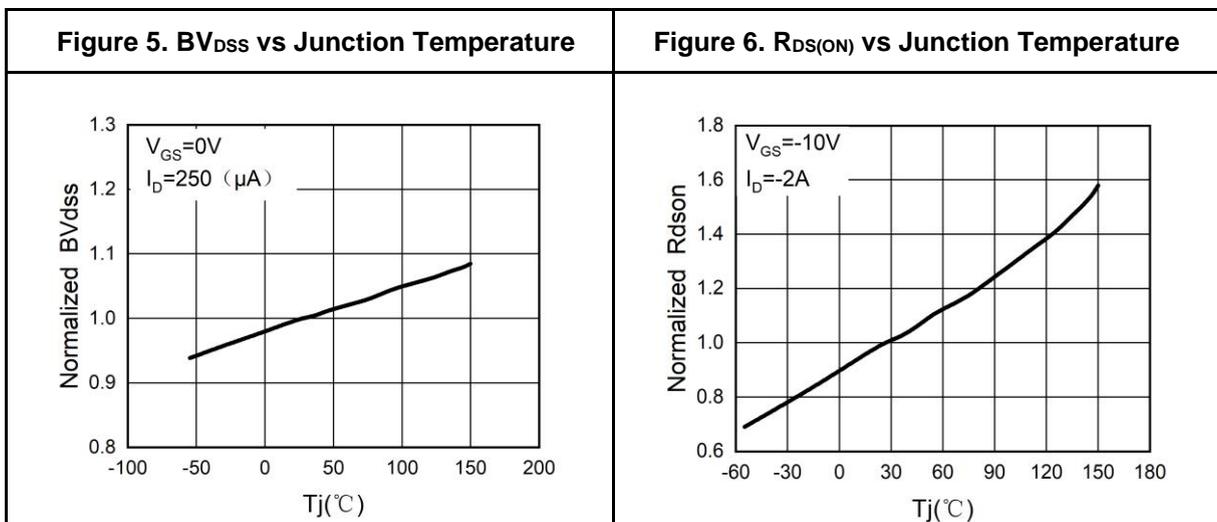
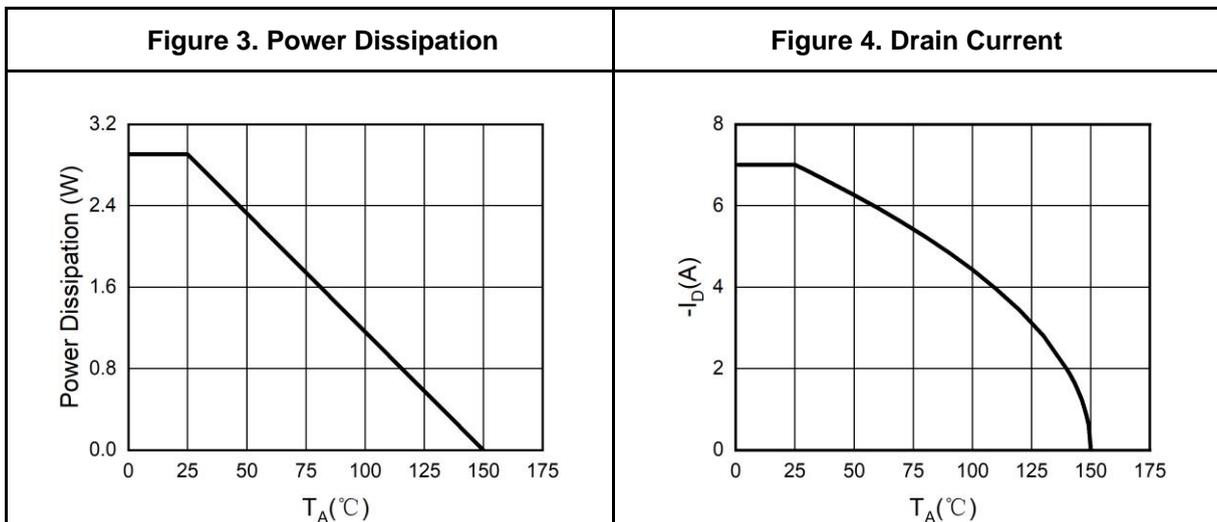
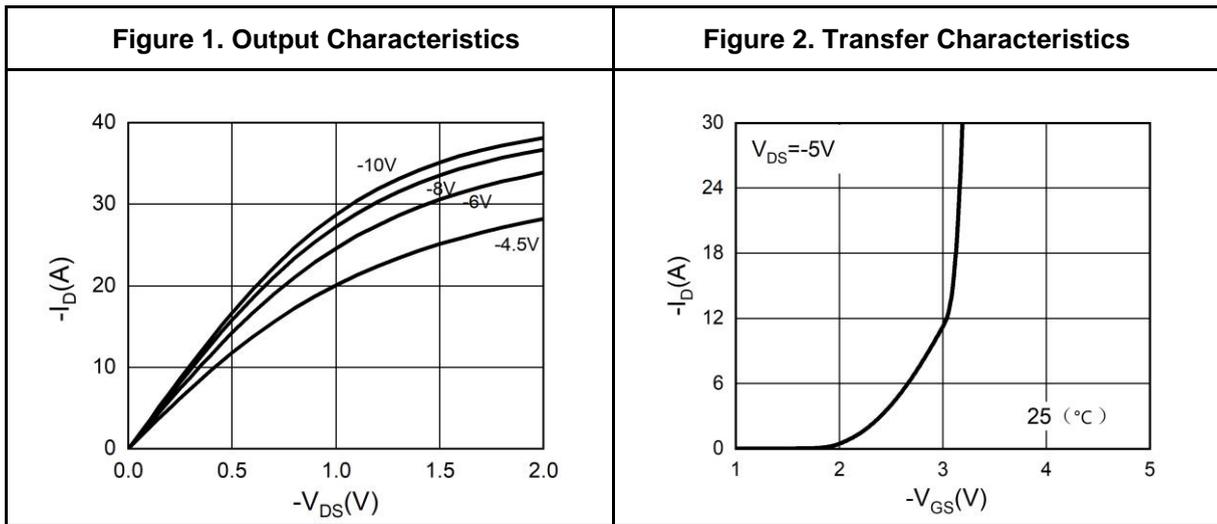
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.EAS condition: $T_J=25^\circ\text{C}, V_{DD}=-30V, V_G=-10V, R_g=25\Omega, L=0.5\text{mH}$.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



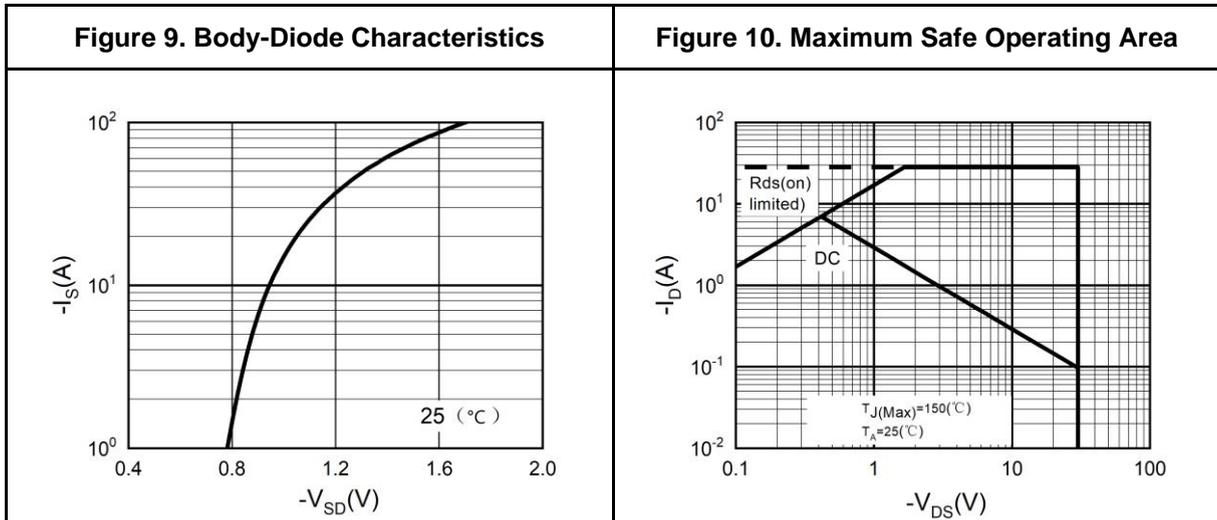
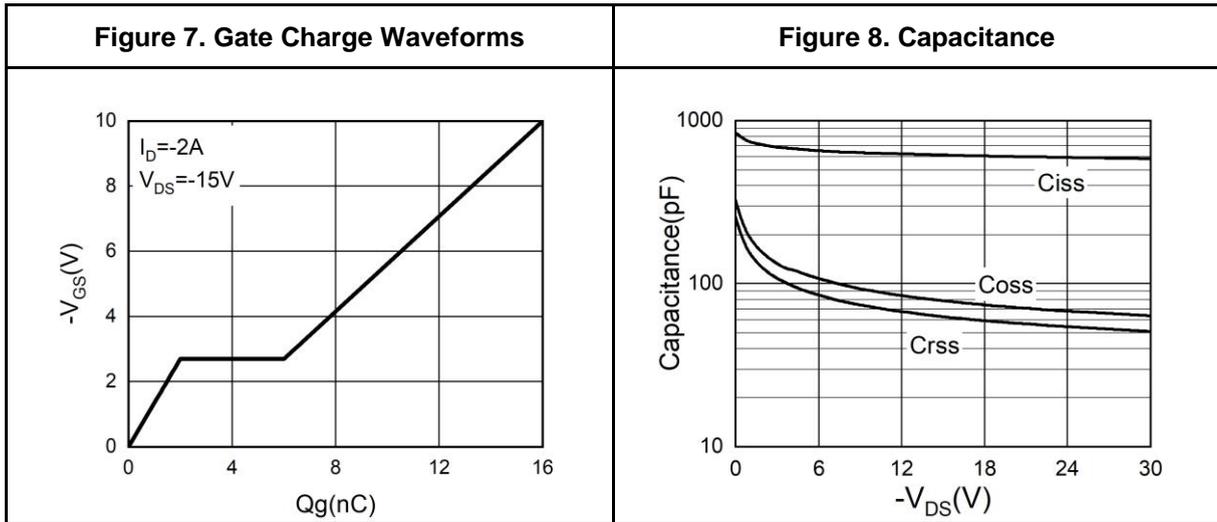
P-Channel Typical Electrical And Thermal Characteristics (Curves)





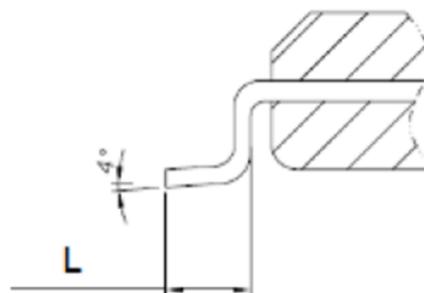
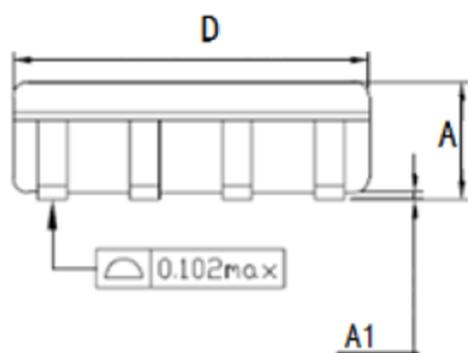
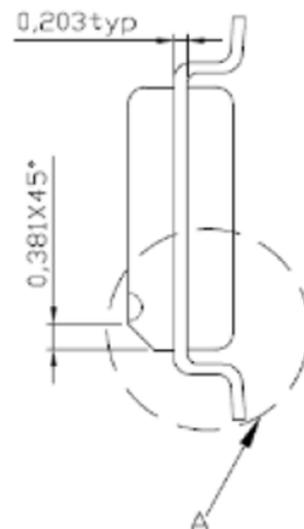
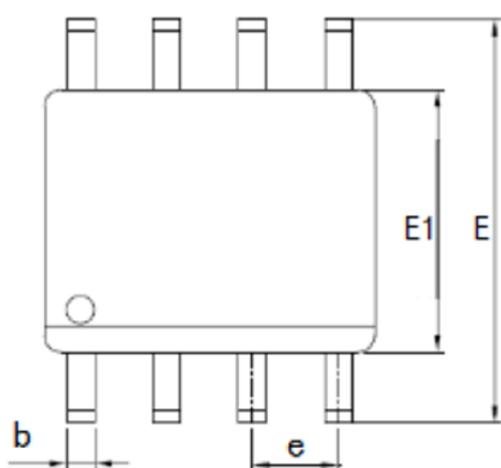
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P-Channel Typical Electrical And Thermal Characteristics (Curves)





SOP-8 Package Information



A 局部放大

Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max
A	1.35	1.55	1.75
A1	0.1	0.15	0.2
b	0.346	0.406	0.466
D	4.8	4.89	4.98
E	5.75	6.00	6.25
E1	3.81	3.90	3.99
e	1.27TYP		
L	0.406	0.838	1.27



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Attention

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